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| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| Поз.Обознач**.** | | **Наименование** | | | | ***Кол.*** | | | **Примечание** | | | |
|  | |  | | | |  | | |  | | | |
| *BA1* | | *Динамик пьезоэлектрический CVS-1508* | | | | *1* | | | *CUI Devices* | | | |
|  | |  | | | |  | | |  | | | |
|  | | *Конденсаторы* | | | |  | | |  | | | |
|  | |  | | | |  | | |  | | | |
| *С1* | | *Электролитический 100 мкФ ECAP -100 В ±20%* | | | | *1* | | | *YAGEO* | | | |
| *С2, C3* | | *Электролитический 10 мкФ ECAP -100 В ±20%* | | | | *2* | | | *YAGEO* | | | |
| *C4..C6* | | *Электролитический 1 мкФ ECAP -100 В ±20%* | | | | *3* | | | *YAGEO* | | | |
| *С7* | | *Электролитический 100 мкФ ECAP -100 В ±20%* | | | | *1* | | | *YAGEO* | | | |
| *C8* | | *Чип керамический 0,1 мкФ 1206-X7R -100 В ±10%* | | | | *1* | | | *JBCapacitors* | | | |
| *C9, C10* | | *Электролитический 1 мкФ ECAP -100 В ±20%* | | | | *2* | | | *YAGEO* | | | |
| *С11, C12* | | *Чип керамический 33 пФ 0805-NPO -50 В ±5%* | | | | *2* | | | *JBCapacitors* | | | |
| *C13..C15* | | *Чип керамический 10 пФ 0805-NPO -50 В ±5%* | | | | *3* | | | *JBCapacitors* | | | |
| *C16..C18* | | *Чип керамический 33 пФ 0805-NPO -50 В ±5%* | | | | *3* | | | *JBCapacitors* | | | |
| *C19, C20* | | *Чип керамический 1 мкФ 0805-X7R -16 В ±10%* | | | | *2* | | | *JBCapacitors* | | | |
|  | |  | | | |  | | |  | | | |
|  | | *Микросхемы* | | | |  | | |  | | | |
|  | |  | | | |  | | |  | | | |
| *DD1* | | *MIC29302WT* | | | | *1* | | | *Microchip Technology* | | | |
| *DD2* | | *NCP1117ST50T3G* | | | | *1* | | | *ON Semiconductor* | | | |
| *DD3* | | *LCD-20X4B* | | | | *1* | | | *Gravitech* | | | |
| *DD4* | | *MAX232* | | | | *1* | | | *Texas Instruments* | | | |
| *DD5, DD6* | | *PCF8574* | | | | *2* | | | *Texas Instruments* | | | |
| *DD7* | | *ATmega328P* | | | | *1* | | | *Atmel Corp.* | | | |
| *DD8* | | *PCF8574* | | | | *1* | | | *Texas Instruments* | | | |
| *DD9* | | *SIM900A* | | | | *1* | | | *SIM Com* | | | |
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|  |  |  |  |  | *ГУИР.425158.001 ПЭ3* | | | | | | | |
|  |  |  |  |  |
| *Изм* | *Лист* | *№ докум* | *Подп.* | *Дата* |
| *Разраб.* | | *Миронь* |  |  | *Система обеспечения безопасности котельной жилого дома на базе микроконтроллера*  *Перечень элементов* | | *Лит* | | | | *Лист* | *Листов* |
| *Пров.* | | *Шемаров* |  |  |  | *Т* | |  | *1* | *2* |
| *Т.контр.* | | *Шемаров* |  |  | *ЭВС, гр. 750701* | | | | | |
| *Н. Контр.* | | *Лихачёв* |  |  |
| *Утв.* | | *Азаров* |  |  |

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| **Обозн.** | | **Наименование** | | | | ***Кол.*** | **Примечание** | |
|  | |  | | | |  |  | |
|  | | *Резисторы* | | | |  |  | |
|  | |  | | | |  |  | |
| *R1* | | *Чип 0805-47 кОм ± 1%* | | | | *1* | *Thick Film* | |
| *R2* | | *Чип 0805-100 кОм ± 1%* | | | | *1* | *Thick Film* | |
| *R3* | | *Чип 0805-510 Ом ± 1%* | | | | *1* | *Thick Film* | |
| *R4* | | *Чип 0805-1 МОм ±1%* | | | | *1* | *Thick Film* | |
| *R5* | | *Чип 0805-4,7 кОм ± 1%* | | | | *1* | *Thick Film* | |
| *R6* | | *Чип 0805-47 кОм ± 1%* | | | | *1* | *Thick Film* | |
| *R7..R9* | | *Чип 0805-22 Ом ± 1%* | | | | *3* | *Thick Film* | |
| R10..R12 | | Чип 0805-4,7 кОм ± 1% | | | | 3 | *Thick Film* | |
| R13..R15 | | Чип 0805-47 кОм ± 1% | | | | 3 | *Thick Film* | |
| R16..R18 | | Чип 0805-510 Ом ± 1% | | | | 3 | *Thick Film* | |
|  | |  | | | |  |  | |
| VD1, VD2 | | SMA4007 | | | | 2 | *WSC Components* | |
| VD3 | | GNL-3012HD | | | | 1 | *G-NOR* | |
| *VD4* | | *GNL-3012YD* | | | | *1* | *G-NOR* | |
| *VD5* | | *GNL-3012GD* | | | | *1* | *G-NOR* | |
|  | |  | | | |  |  | |
| *VT1..VT4* | | *КТ3102АМ* | | | | *4* | *Nexperia* | |
|  | |  | | | |  |  | |
| *XS1* | | *ADC-029* | | | | *1* | *EQUAL* | |
| XS2 | | DS1023-1x7 | | | | 1 | *LEOCO* | |
| *XS3* | | *RS-232* | | | | *1* | *CVILUX* | |
| *XS4* | | *DS1013-24S* | | | | *1* | *CONNFLY* | |
| *XS5* | | *KLS5-CR2032-01* | | | | *1* | *KLS Electronics* | |
| *XS6* | | *SIM5051-6-0-18-00-A* | | | | *1* | *Future Electronics* | |
| *XS7* | | *RECE.20279.001E.01* | | | | *1* | *Taoglas* | |
|  | |  | | | |  |  | |
| *ZQ1* | | *Резонатор кварцевый Q 8МГц HC-49S* | | | | *1* | *Rami Technology* | |
|  | |  | | | |  |  | |
|  | |  | | | |  |  | |
|  |  |  |  |  | *ГУИР.421457.001 ПЭ3* | | | *Лист* |
|  |  |  |  |  | *2* |
| *Изм* | *Лист* | *№ докум* | *Подп.* | *Дата* |